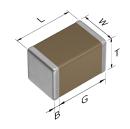
C2012X6S1V225M085AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012X6S1V225MT****	
用途	一般等级	
特点	General 一般(~75V)	
系列	C2012 [EIA 0805]	
状态	▲ 量产体制(新设计非推荐)推荐代替型号 : C2012X7R1V225K125AB (不保证其兼容性。)	



尺寸		
长度(L)	2.00mm ±0.20mm	
宽度(W)	1.25mm ±0.20mm	
厚度(T)	0.85mm ±0.15mm	
端子宽度(B)	0.20mm Min.	
端子间隔(G)	0.50mm Min.	
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)	
推存序益和向 (FA)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
证书/杆皿:叩/叨 (t D)	0.70mm to 0.90mm(Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
1年行行並作内はい	0.90mm to 1.20mm(Reflow Soldering)	

电气特性		
电容	2. 2 μ F ±20%	
额定电压	35VDC	
温度特性	$X6S(\pm 22\%)$	
耗散因数(Max.)	5%	
绝缘电阻 (Min.)	227M Ω	

	其他	
焊接方法	流体	
件按刀伍	回流	
AEC-Q200	NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.



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特性图表(这是参考数据,并不保证产品的特性。)

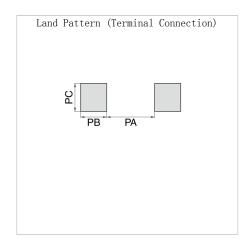
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Associated Images



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